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PATENT APPLICATION

TECHNOLOGY CENTER 2800  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Satoshi TAKANO

Group Art Unit: 2825

Application No.: 09/819,690

Examiner: G. Lee

Filed: March 29, 2001

Docket No.: 109107

For: SEMICONDUCTOR MANUFACTURING METHOD, SUBSTRATE PROCESSING  
METHOD, AND SEMICONDUCTOR MANUFACTURING APPARATUS

**SUPPLEMENTAL AMENDMENT**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

Further to the Amendment filed April 7, 2003, please further amend the above-  
identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 7 and 8 without prejudice to or disclaimer of the subject matter  
contained therein.

Please replace claims 1-3, 6 and 9-11 as follows:

- 
1. (Twice Amended) A semiconductor manufacturing method, comprising the  
steps of:
- exchanging a substrate between a preliminary chamber and an external part;  
subjecting the substrate to predetermined processing in a process chamber; and  
transferring the substrate through a transfer chamber provided between said  
preliminary chamber and said process chamber,
- wherein said substrate transferring step comprises the following three steps:
- B 1*